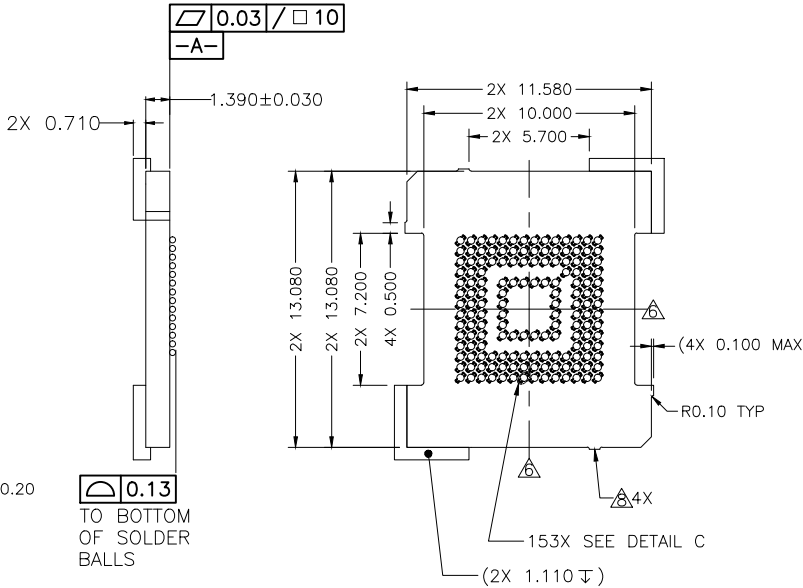
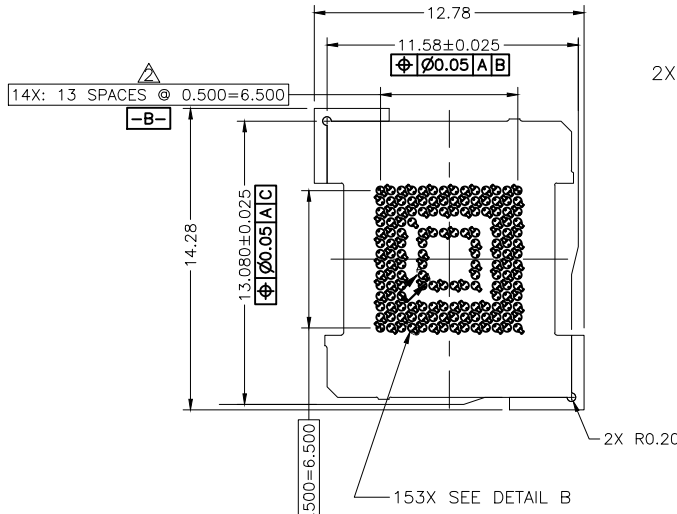
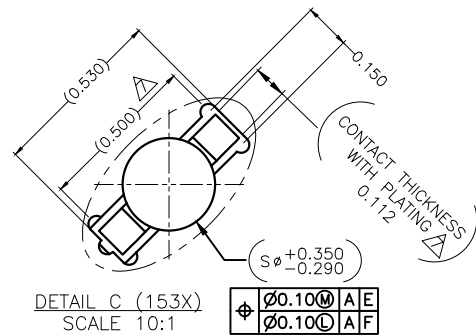
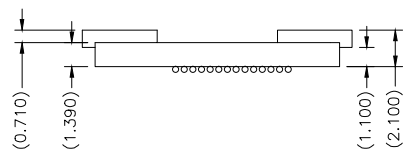


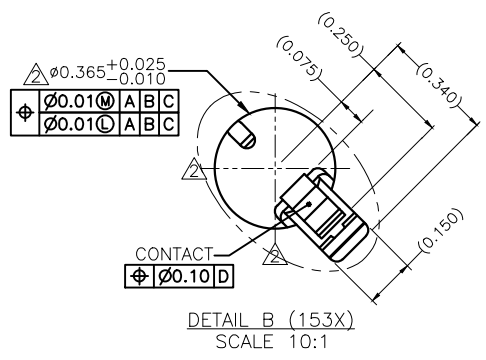
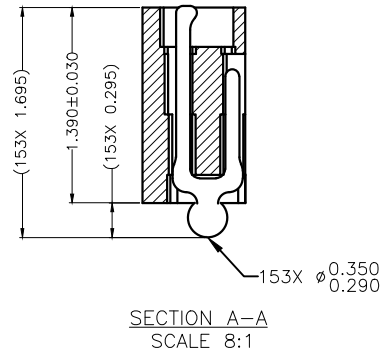
REV	ECO	BY	DESCRIPTION	APV	DATE
A	31477	RS	Initial Design	NSJ	02/26/14



- NOTES:
- Reference HSI0 Technologies specification 700001-0001 for solder attachment.
  - Locates center of contact/ slot.
  - Reference HSI0 Technologies specification 700001-0002 for application notes.
  - Footprint part number is 104311-0371.
  - Datums **-B-** and **-C-** are defined by  $\phi 0.365$  features on corner slots.
- $\triangle$  **-E-** Center of ball pattern.  
 $\triangle$  **-F-** Center of contact.  
 $\triangle$  Tooling marks permitted. Maximum 0.10 protrusion (shown).



Parts List	
Part Number	Description
103864-0128	PRESS, DEVICE INSERT, GRYP 11.5X13 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL 4 X 53 (SOLD SEPARATELY)
104553-0330	STEN, FLEX, 153G4011.5X13-0.50 (SOLD SEPARATELY)



UNLESS OTHERWISE SPECIFIED - DIMENSIONS ARE IN MILLIMETERS - DIM'S APPLY AFTER PLATING

TOLERANCES UNLESS OTHERWISE NOTED:

ANGLES	DECIMALS	±"
±1°	±0.25	
±1°	±0.10	
±1°	±0.050	

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CAD GENERATED DRAWING DO NOT MANUALLY UPDATE

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MAPLE GROVE, MN 55311. 763-447-6260

DRAWING APPROVALS

NAME	DATE	TITLE
R. Sewharack	02/26/14	SCKT, 153G4011.5X13-0.50 WITH EUTECTIC SOLDER BALLS
N. St Jacques	02/26/14	

LEGEND:

- $\triangle$  NOTE CALLOUT
- $\textcircled{1}$  REVISION CHANGE
- $\textcircled{X}$  ITEM NUMBER

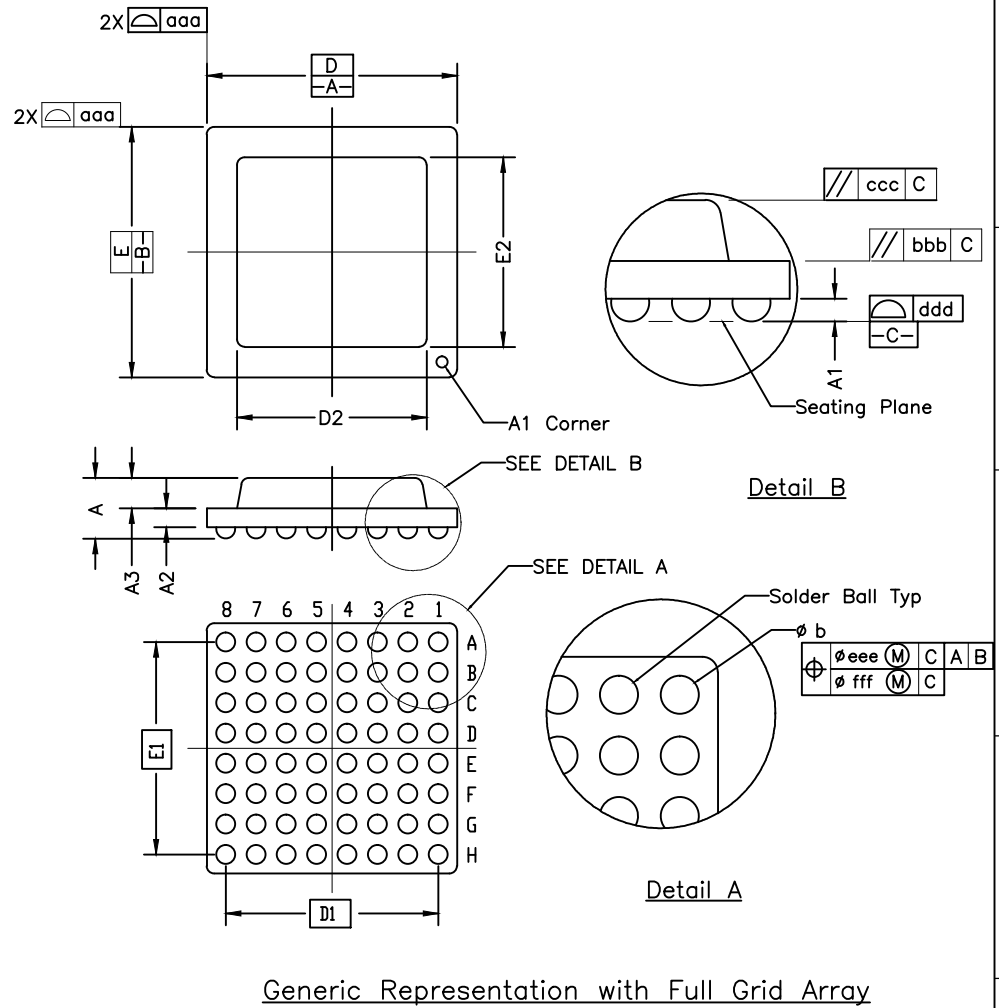
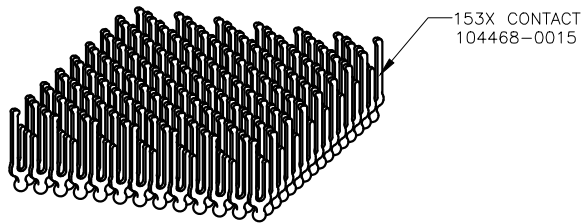
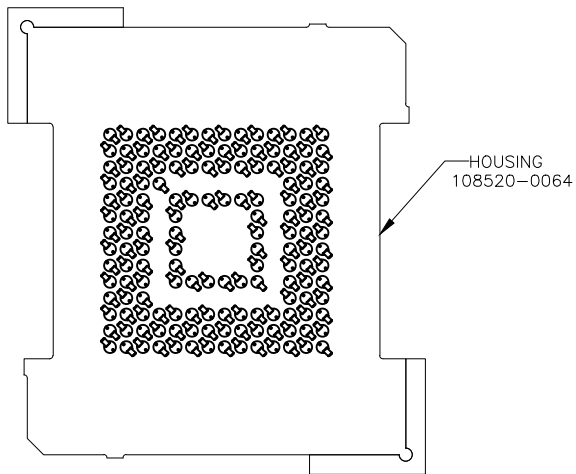
REV	CAD FORMAT	DRAWING NO.	MATERIAL	SCALE	DATE	REV.
C	AUTOCAD	108387-0064	Cirlex			A

THIRD ANGLE PROJECTION

1 of 2

SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	N	153	Package Size	D	11.50
Columns	ND	14		E	13.00
Rows	NE	14	Ball Spacing	D1	6.500
Pitch	e	0.50		E1	6.500
Ball Size	b	0.35±0.05	Encapsulant/ Top Size	D2	n/a
Total Thickness	A	n/a		E2	n/a
Ball Height	A1	0.225 MIN	Pattern Style	Irregular*	
Substrate Thickness	A2	n/a	Perimeter Rows	n/a	
Top Thickness	A3		Center Array	n/a	
Form Tolerances					
Edge	aaa	0.10	Bottom	ddd	0.08
Substrate	bbb	0.10	Position	eee	0.15
top	ccc	0.10	Position	fff	0.05

All dimensions are in millimeters.  
\* See footprint for pattern details.



Generic Representation with Full Grid Array

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- DIMENSIONS ARE IN MILLIMETERS  
- DIM'S APPLY AFTER PLATING

TOLERANCES UNLESS OTHERWISE NOTED:  
ANGLES DECIMALS  
±1° X.XX ±0.25  
X.XX ±0.10  
X.XXX ±0.050

LEGEND:  
⊕ NOTE CALLOUT  
Ⓜ REVISION CHANGE  
Ⓧ ITEM NUMBER

HSIQ TECHNOLOGIES, LLC.  
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MAPLE GROVE, MN 55311. 763-447-6260

TITLE  
SCKT, 153G4011.5X13-0.50  
WITH EUTECTIC SOLDER BALLS

SIZE C CAD FORMAT AUTOCAD DRAWING NO. 108387-0064 REV. A

SCALE MATERIAL See Pg 1 SHEET 2 of 2